



NEO 200A

Resist strip /
descum

High dose
implant strip

Etching



— When plasma matters



NEO 200A



The NEO 200A product is the smallest footprint single chamber platform for advanced ashing and etching products from Trymax Semiconductor Equipment.

It's a fully automated single chamber system that can be configured with any of the currently available Trymax NEO process modules. It's compatible with substrates up to 200mm in diameter. The small footprint of the NEO 200A is configured with a dual cassette.

Features

- 100/150/200mm substrate size
- Dual cassette platform
- 4 axis dual arm robot handling
- 4 different process chamber technologies available:
 - Microwave downstream (2.45 GHz)
 - RF bias (13.56 MHz)
 - Dual Source (Microwave, RF bias)
 - CCP Top RF powered (13.56Mhz)
- Mechanical throughput >100wph
- Compact footprint
- Very low Cost of Ownership
- Fully digital controlled, devicenet-ethernet
- Windows based industrial computers
- Single slot cooling station
- Front and rear user interfaces

Options

- Fab host control SECS-II

Applications

- Bulk resist, post LDI resist strip
- Descum processing
- Polymer removal
- Post high dose implant strip
- Silicon nitride/silicon carbide etch applications
- TaSi etch
- MEMS applications
- Advanced packaging processing (PR, PI, BCB, PBO)
- RF filter BAW/SAW resist processing

Compliance

- CE EU-RoHs
- UL (optional)



Contact us now

Trymax Semiconductor Equipment BV

Bijsterhuizen 11-52
6546 AS Nijmegen
The Netherlands

T +31 (0)24 350 08 09
F +31 (0)24 354 16 16
E sales@trymax-semiconductor.com

www.trymax-semiconductor.com